

**BT139 800T****THREE QUADRANT TRIACS***Blocking voltage to 800Volts On-state RMS current to 16.0 Ampere***FEATURES**

- Ultra low gate trigger current
- Low cost package

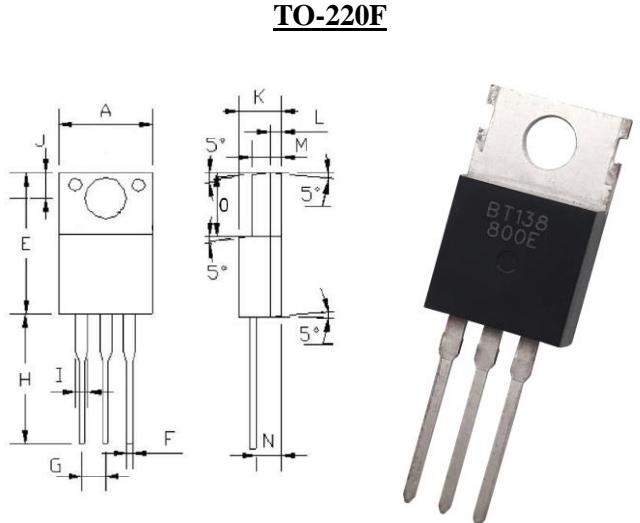
**APPLICATIONS**

• Typical applications include motor control, industrial and domestic lighting, heating and static switching

- Heating regulation
- Motor control
- Phase control

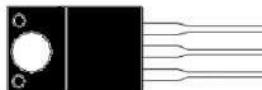
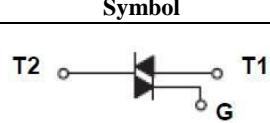
**DESCRIPTION**

Glass passivated high commutation triacs in a full pack, plastic envelope intended for use in circuits where high static and dynamic dV/dt and high dI/dt can occur. These devices will commute the full rated rms current at the maximum rated junction temperature, without the aid of a snubber.



DIM	Inches		Milimeters		DIM	Inches		Milimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.396	0.404	10.05	10.25	J	0.123	0.131	3.13	3.33
E	0.618	0.63	15.7	16	K	0.182	0.186	4.63	4.73
F	0.028	0.035	0.7	0.9	L	0.030(TYP.)		0.77(TYP.)	
G	0.093	0.108	2.35	2.75	M	0.097	0.101	2.47	2.57
H	0.5	0.512	12.7	13	N	0.104	0.112	2.65	2.85
I	0.049	0.057	1.24	1.44	O	0.258	0.262	6.55	6.65

**PINNING INFORMATION**

PIN	Description	Simplified outline	Symbol
1	main terminal 1(T1)	 TO-220F	
-	-		
3	gate(G)		

**QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX	UNIT
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltages	800	V
$I_{T(RMS)}$	RMS on-state current	16	A
$I_{TSM}$	Non-repetitive peak on-state current	120	A

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$R_{th j-mb}$	Thermal resistance junction to mounting base	full cycle	-	-	1.5	K/W
		half cycle	-	-	2.0	K/W
$R_{th j-a}$	Thermal resistance junction to ambient	in free air		60	-	K/W

**BT139 800T****THREE QUADRANT TRIACS***Blocking voltage to 800Volts On-state RMS current to 16.0 Ampere***LIMITING VALUE**

Limiting values in accordance with the Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; T <sub>mb</sub> <= 102 °C	-	16	A
	Non-repetitive peak on-state current	full sine wave; T <sub>j</sub> = 25 °C prior to surge	t = 20 ms t = 16.7 ms	120 140	A
I <sup>2</sup> t	I <sup>2</sup> t for fusing	t = 10 ms	-	45	A <sup>2</sup> s
dI <sub>T</sub> /dt	Repetitive rate of rise of on-state current after triggering	I <sub>TM</sub> = 16 A; I <sub>G</sub> = 0.2 A; DI <sub>G</sub> /dt = 0.2 A/s	T2+ G+ T2- G-	100 100	A/μs A/μs
I <sub>GM</sub>	Peak gate current		-	2	A
V <sub>GM</sub>	Peak gate voltage		-	8	V
P <sub>GM</sub>	Peak gate power		-	16	W
P <sub>G(AV)</sub>	Average gate power	over any 20 ms period	-	0.35	W
T <sub>stg</sub>	Storage temperature		-40	150	°C
T <sub>j</sub>	Junction temperature		-40	125	°C

**CHARACTERISTICS**T<sub>j</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
<b>Static characteristics</b>						
I <sub>GT</sub>	Gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A				
			T2+ G+	-	10	35
			T2+ G-	-	15	35
			T2- G-	-	15	35
I <sub>L</sub>	Latching current	V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1A				
			T2+ G+	-	20	50
			T2+ G-	-	30	80
			T2- G-	-	20	50
I <sub>H</sub>	Holding current	V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.15A				
V <sub>T</sub>	On-state voltage	I <sub>T</sub> = 20A				
V <sub>GT</sub>	Gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1A				
			T2+ G+	0.5	0.78	1.5
			T2+ G-	0.5	0.70	1.5
			T2- G-	0.5	0.71	1.5

**Dynamic Characteristics**

dV <sub>D</sub> /dt	Critical rate of rise of off-state voltage	V <sub>DM</sub> = 67% V <sub>DRM(max)</sub> ; T <sub>j</sub> = 125 °C; Exponential wave form; gate open circuit	250	500	-	V/μs
dI <sub>com</sub> /dt	Critical rate of change of commutating current	V <sub>D</sub> = 400 V; T <sub>j</sub> = 125 °C I <sub>T(RMS)</sub> =4.4A; Commutating d <sub>v</sub> /dt = 18V/s, Without snubber; gate open circuit	6.5	-	-	A/ms
dI/dt	Repetitive Critical Rate of Rise of On-State Current	I <sub>PK</sub> = 50A; PW = 40sec; dI <sub>G</sub> /dt = 200mA/set; f = 60Hz	-	-	10	A/μs

## RATINGS AND CHARACTERISTIC CURVES BT139 800T

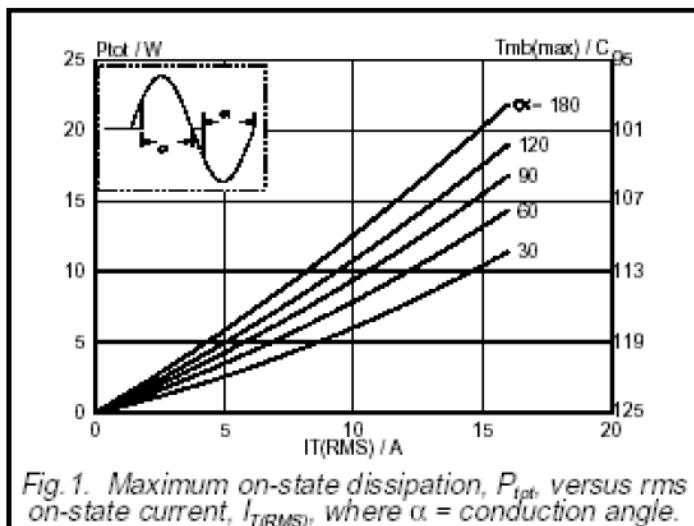


Fig. 1. Maximum on-state dissipation,  $P_{diss}$ , versus rms on-state current,  $I_T(RMS)$ , where  $\alpha$  = conduction angle.

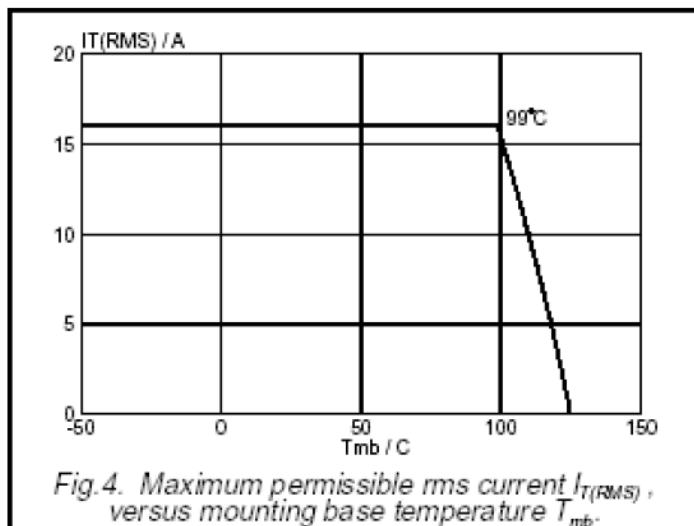


Fig. 4. Maximum permissible rms current  $I_T(RMS)$ , versus mounting base temperature  $T_{mb}$ .

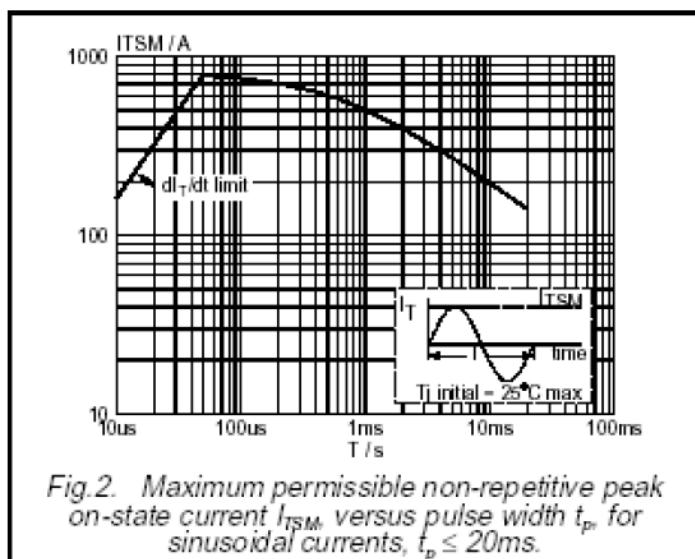


Fig. 2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \leq 20\text{ms}$ .

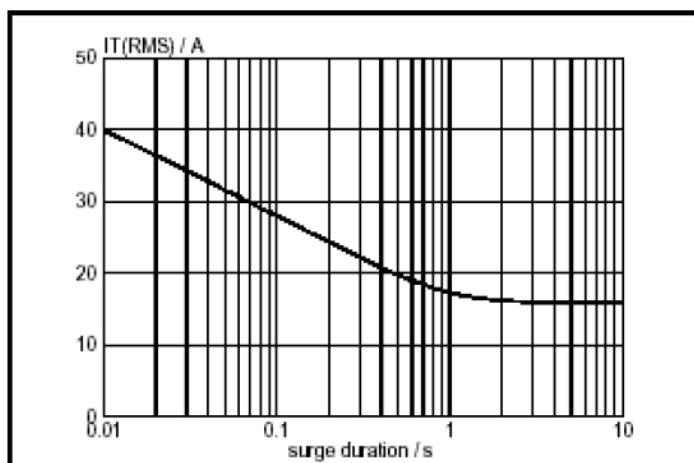


Fig. 5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents,  $f = 50\text{Hz}$ ;  $T_{mb} \leq 99^\circ\text{C}$ .

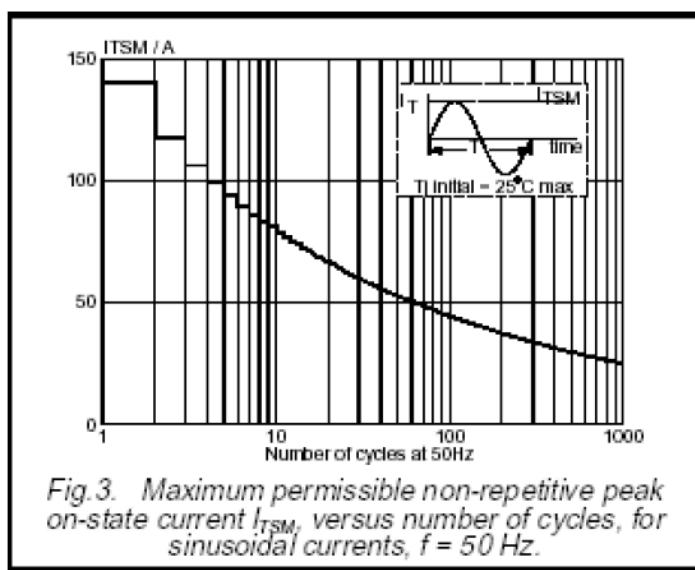


Fig. 3. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents,  $f = 50\text{Hz}$ .

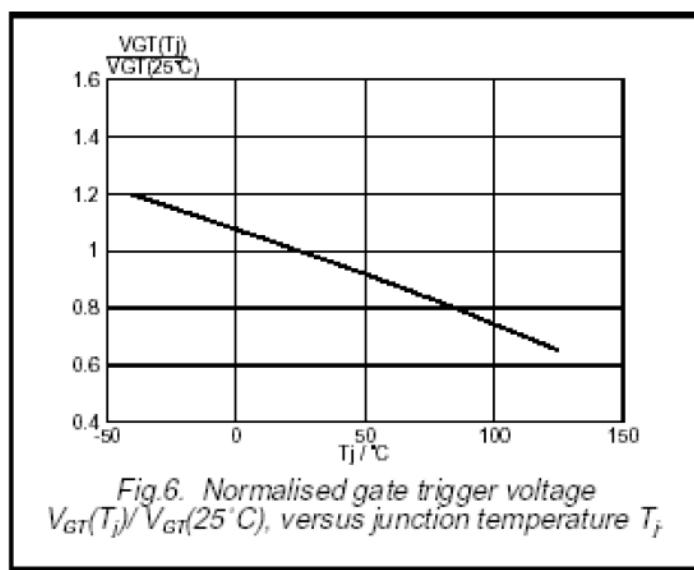


Fig. 6. Normalised gate trigger voltage  $V_{GT}(T_j)/V_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

Note: Specification are subject to change without notice. For more detail and update, please visit our website.

## RATINGS AND CHARACTERISTIC CURVES BT139 800T

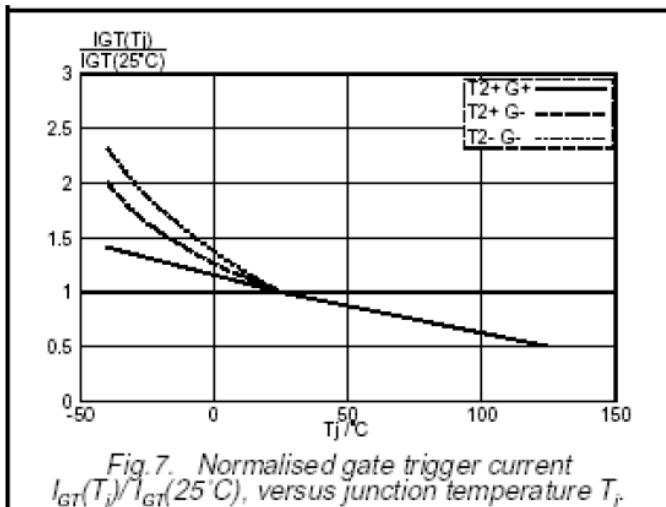


Fig. 7. Normalised gate trigger current  $I_{GT}(T_j)/I_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

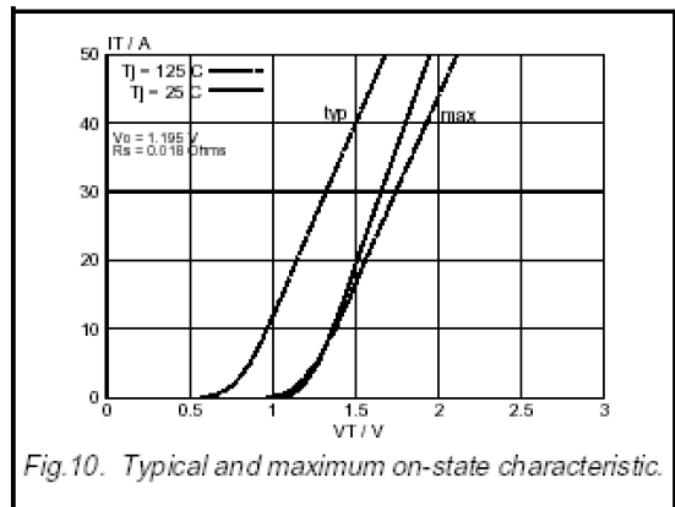


Fig. 10. Typical and maximum on-state characteristic.

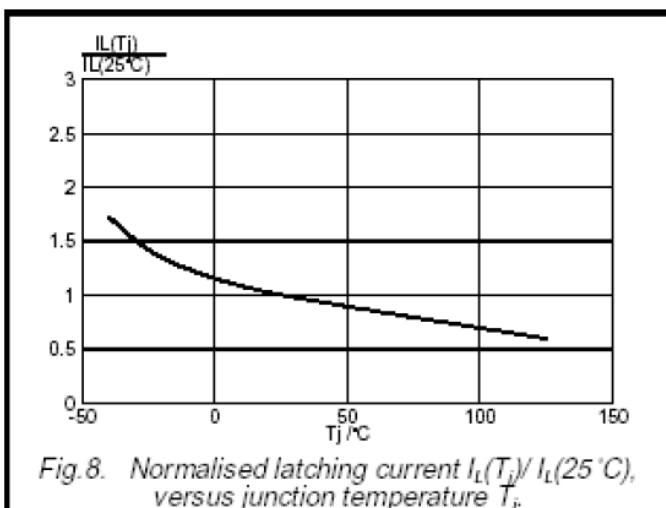


Fig. 8. Normalised latching current  $I_L(T_j)/I_L(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

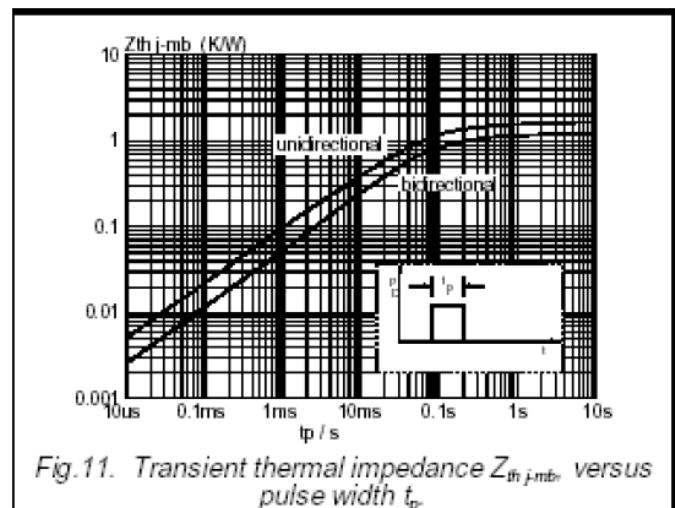


Fig. 11. Transient thermal impedance  $Z_{th(j\text{-}mb)}$ , versus pulse width  $t_p$ .

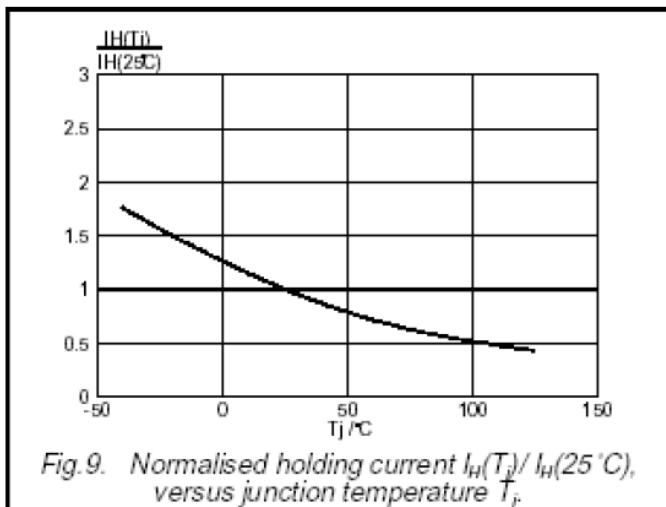


Fig. 9. Normalised holding current  $I_H(T_j)/I_H(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

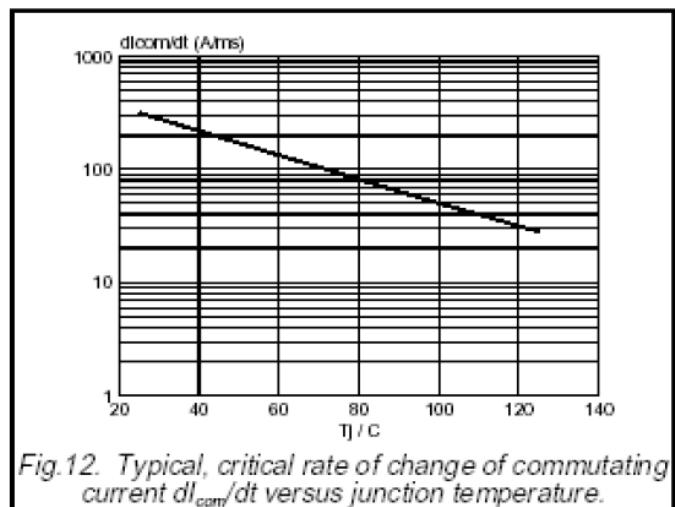


Fig. 12. Typical, critical rate of change of commutating current  $dl_{com}/dt$  versus junction temperature.

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